Darlington Complementary Silicon Power Transistors

Designed for general-purpose amplifier and low frequency switching applications.

Features

• High DC Current Gain -

Min h_{FE} = 1000 @ I_C
=
$$5.0 \text{ A}, V_{CE} = 4 \text{ V}$$

• Collector-Emitter Sustaining Voltage - @ 30 mA

- Monolithic Construction with Built-In Base-Emitter Shunt Resistor
- These are Pb-Free Devices*

MAXIMUM RATINGS

Rating	Symbol	TIP140 TIP145	TIP141 TIP146	TIP142 TIP147	Unit
Collector - Emitter Voltage	V _{CEO}	60	80	100	Vdc
Collector - Base Voltage	V _{CB}	60	80	100	Vdc
Emitter - Base Voltage	V _{EB}	5.0		Vdc	
Collector Current - Continuous - Peak (Note 1)	I _C	10 15		Adc	
Base Current - Continuous	Ι _Β	0.5		Adc	
Total Power Dissipation @ T _C = 25°C	P _D	125		W	
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-65 to +150		°C	

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.0	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	35.7	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

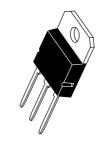
1. 5 ms, ≤ 10% Duty Cycle.



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10 AMPERE DARLINGTON COMPLEMENTARY SILICON POWER TRANSISTORS 60-100 VOLTS, 125 WATTS



SOT-93 (TO-218) CASE 340D STYLE 1



TO-247 CASE 340L STYLE 3

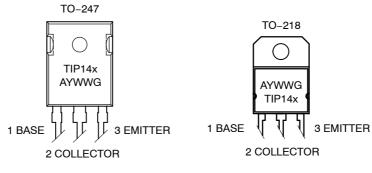
NOTE: Effective June 2012 this device will be available only in the TO-247 package. Reference FPCN# 16827.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MARKING DIAGRAMS



 TIP14x
 = Device Code

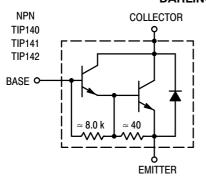
 A
 = Assembly Location

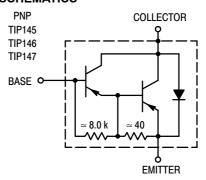
 Y
 = Year

 WW
 = Work Week

 G
 = Pb-Free Package

DARLINGTON SCHEMATICS





ORDERING INFORMATION

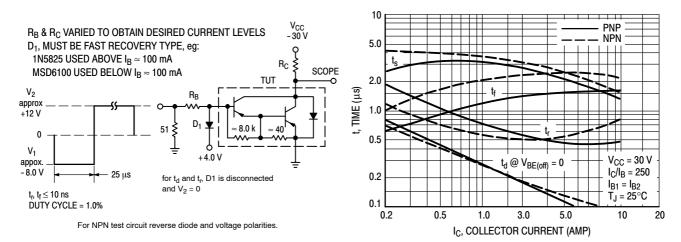
Device	Package	Shipping
TIP140G	SOT-93 (TO-218) (Pb-Free)	30 Units / Rail
TIP141G	SOT-93 (TO-218) (Pb-Free)	30 Units / Rail
TIP142G	SOT-93 (TO-218) (Pb-Free)	30 Units / Rail
TIP145G	SOT-93 (TO-218) (Pb-Free)	30 Units / Rail
TIP146G	SOT-93 (TO-218) (Pb-Free)	30 Units / Rail
TIP147G	SOT-93 (TO-218) (Pb-Free)	30 Units / Rail
TIP140G	TO-247 (Pb-Free)	30 Units / Rail
TIP141G	TO-247 (Pb-Free)	30 Units / Rail
TIP142G	TO-247 (Pb-Free)	30 Units / Rail
TIP145G	TO-247 (Pb-Free)	30 Units / Rail
TIP146G	TO-247 (Pb-Free)	30 Units / Rail
TIP147G	TO-247 (Pb-Free)	30 Units / Rail

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS	<u>.</u>					
Collector-Emitter Sustaining Voltage (Note 2)		V _{CEO(sus)}				Vdc
$(I_C = 30 \text{ mA}, I_B = 0)$	TIP140, TIP145	020(000)	60	_	_	
	TIP141, TIP146		80	_	_	
	TIP142, TIP147		100	-	-	
Collector Cutoff Current		I _{CEO}				mA
$(V_{CE} = 30 \text{ Vdc}, I_{B} = 0)$	TIP140, TIP145		_	_	2.0	
$(V_{CE} = 40 \text{ Vdc}, I_{B} = 0)$	TIP141, TIP146		_	_	2.0	
$(V_{CE} = 50 \text{ Vdc}, I_B = 0)$	TIP142, TIP147		-	-	2.0	
Collector Cutoff Current		I _{CBO}				mA
$(V_{CB} = 60 \text{ V}, I_{E} = 0)$	TIP140, TIP145		_	_	1.0	
$(V_{CB} = 80 \text{ V}, I_{E} = 0)$	TIP141, TIP146		_	_	1.0	
$(V_{CB} = 100 \text{ V}, I_{E} = 0)$	TIP142, TIP147		_	-	1.0	
Emitter Cutoff Current (V _{BE} = 5.0 V)		I _{EBO}	-	-	20	mA
ON CHARACTERISTICS (Note 2)						
DC Current Gain		h _{FE}				_
$(I_C = 5.0 \text{ A}, V_{CE} = 4.0 \text{ V})$			1000	_	_	
$(I_C = 10 \text{ A}, V_{CE} = 4.0 \text{ V})$			500	-	-	
Collector-Emitter Saturation Voltage		V _{CE(sat)}				Vdc
$(I_C = 5.0 \text{ A}, I_B = 10 \text{ mA})$			_	_	2.0	
$(I_C = 10 \text{ A}, I_B = 40 \text{ mA})$			_	-	3.0	
Base-Emitter Saturation Voltage		V _{BE(sat)}	-	-	3.5	Vdc
$(I_C = 10 \text{ A}, I_B = 40 \text{ mA})$. ,				
Base-Emitter On Voltage		V _{BE(on)}	_	-	3.0	Vdc
$(I_C = 10 \text{ A}, V_{CE} = 4.0 \text{ Vdc})$. ,				
SWITCHING CHARACTERISTICS						
Resistive Load (See Figure 1)						
Delay Time		t _d	-	0.15	-	μs
Rise Time $(V_{CC} = 30 \text{ V}, I_C = 5.0 \text{ A},$	0/	t _r	_	0.55	-	μs
$I_{B} = 20 \text{ mA}, \text{ Duty Cycle} \leq 2.0$						

^{2.} Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.

Fall Time



 t_f

Figure 1. Switching Times Test Circuit

Figure 2. Switching Times

2.5

μS

TYPICAL CHARACTERISTICS

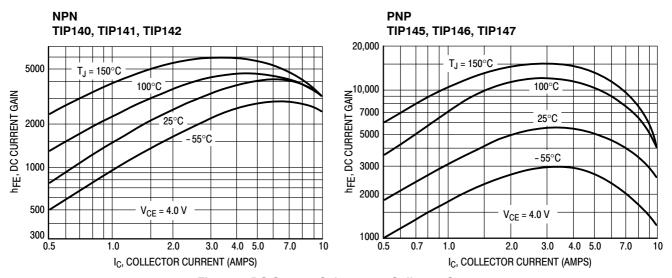


Figure 3. DC Current Gain versus Collector Current

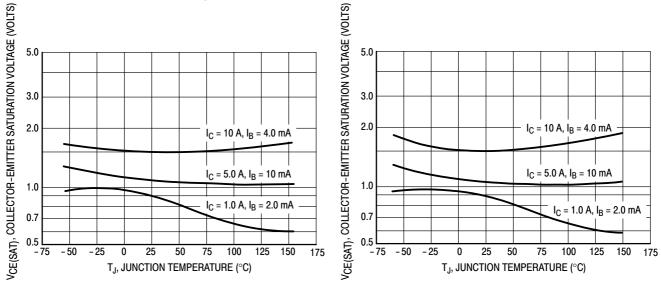


Figure 4. Collector-Emitter Saturation Voltage

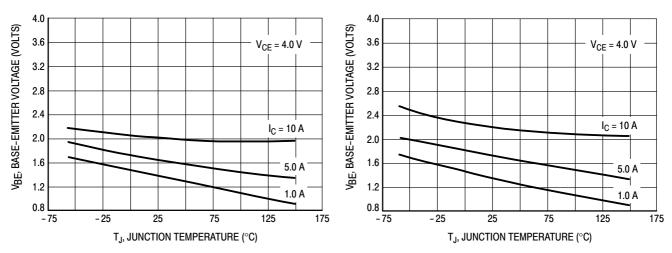


Figure 5. Base-Emitter Voltage

ACTIVE-REGION SAFE OPERATING AREA

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate I_C – V_{CE} limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 6 is based on $T_{J(pk)} = 150^{\circ}\text{C}$; T_{C} is variable depending on conditions. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

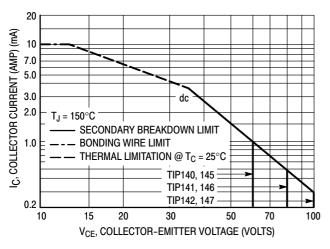


Figure 6. Active-Region Safe Operating Area

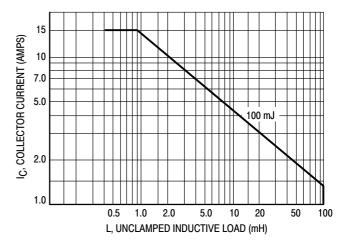
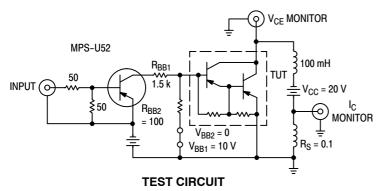
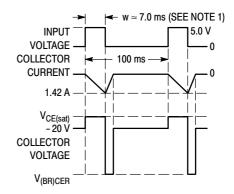


Figure 7. Unclamped Inductive Load



NOTE 1: Input pulse width is increased until I_{CM} = 1.42 A.

NOTE 2: For NPN test circuit reverse polarities.



VOLTAGE AND CURRENT WAVEFORMS

Figure 8. Inductive Load

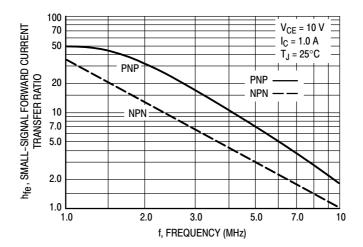


Figure 9. Magnitude of Common Emitter Small-Signal Short-Circuit Forward Current Transfer Ratio

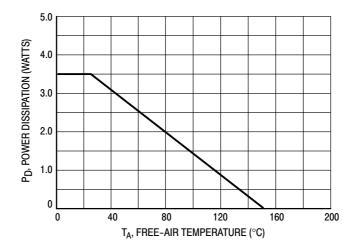
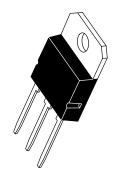


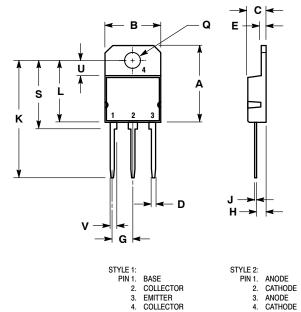
Figure 10. Free-Air Temperature Power Derating



SOT-93 (TO-218) CASE 340D-02 **ISSUE E**

DATE 01/03/2002

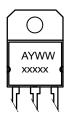




- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.

			INCHES		
	MILLIMETERS		INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α		20.35		0.801	
В	14.70	15.20	0.579	0.598	
С	4.70	4.90	0.185	0.193	
D	1.10	1.30	0.043	0.051	
Е	1.17	1.37	0.046	0.054	
G	5.40	5.55	0.213	0.219	
Н	2.00	3.00	0.079	0.118	
7	0.50	0.78	0.020	0.031	
K	31.00	REF	1.220 REF		
L		16.20		0.638	
Q	4.00	4.10	0.158	0.161	
S	17.80	18.20	0.701	0.717	
U	4.00 REF		0.157 REF		
V	1 75 RFF		0.0	169	

MARKING DIAGRAM



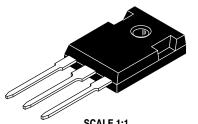
= Assembly Location

= Year

WW = Work Week XXXXX = Device Code

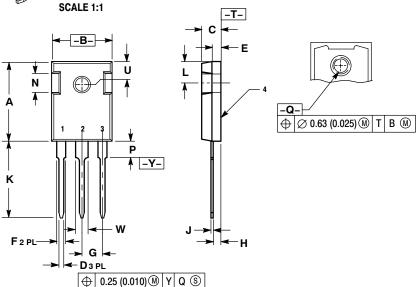
DOCUMENT NUMBER:	98ASB42643B Electronic versions are uncontrolled except when accessed directly from the Docu- Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in		
DESCRIPTION:	SOT-93		PAGE 1 OF 1

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TO-247 CASE 340L-02 ISSUE F

DATE 26 OCT 2011



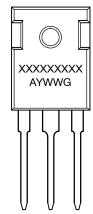
STYLE 2: PIN 1. ANODE 2. CATHODE (S) STYLE 4:
PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR STYLE 1: PIN 1. GATE 2. DRAIN STYLE 3: PIN 1. BASE 2. COLLECTOR 3. SOURCE 4. DRAIN 3. ANODE 2 4. CATHODES (S) 3. EMITTER 4. COLLECTOR STYLE 5: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE STYLE 6: PIN 1. MAIN TERMINAL 1 2. MAIN TERMINAL 2

3. GATE 4. MAIN TERMINAL 2

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	20.32	21.08	0.800	8.30
В	15.75	16.26	0.620	0.640
С	4.70	5.30	0.185	0.209
D	1.00	1.40	0.040	0.055
Е	1.90	2.60	0.075	0.102
F	1.65	2.13	0.065	0.084
G	5.45	5.45 BSC		BSC
Н	1.50	2.49	0.059	0.098
J	0.40	0.80	0.016	0.031
K	19.81	20.83	0.780	0.820
L	5.40	6.20	0.212	0.244
N	4.32	5.49	0.170	0.216
P		4.50		0.177
Q	3.55	3.65	0.140	0.144
U	6.15 BSC		0.242	BSC
W	2.87	3.12	0.113	0.123

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code = Assembly Location

Υ = Year WW = Work Week G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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98ASB15080	C

PAGE 2 OF 2

ISSUE	REVISION	DATE
D	CHANGE OF OWNERSHIP FROM MOTOROLA TO ON SEMICONDUCTOR. DIM A WAS 20.80-21.46/0.819-0.845. DIM K WAS 19.81-20.32/0.780-0.800. UPDATED STYLE 1, ADDED STYLES 2, 3, & 4. REQ. BY L. HAYES.	25 AUG 2000
E	DIM E MINIMUM WAS 2.20/0.087. DIM K MINIMUM WAS 20.06/0.790. ADDED GENERIC MARKING DIAGRAM. REQ. BY S. ALLEN.	26 FEB 2010
F	ADDED STYLES 5 AND 6. REQ. BY J. PEREZ.	26 OCT 2011

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